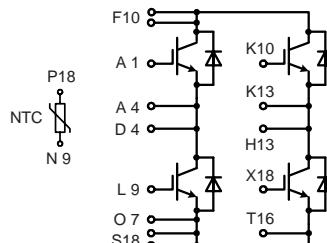


IGBT Modules in ECO-PAC 2

H-Bridge configuration

Short Circuit SOA Capability
Square RBSOA

I_{C25} = 49 A
 V_{CES} = 1200 V
 $V_{CE(sat)\text{ typ.}}$ = 3.1 V



Pin arrangement see outlines

IGBTs

Symbol	Conditions	Maximum Ratings		
V_{CES}	$T_{VJ} = 25^\circ\text{C}$ to 150°C	1200	V	
V_{GES}		± 20	V	
I_{C25}	$T_c = 25^\circ\text{C}$	49	A	
I_{C80}	$T_c = 80^\circ\text{C}$	33	A	
I_{CM}	$V_{GE} = \pm 15 \text{ V}$; $R_G = 47 \Omega$; $T_{VJ} = 125^\circ\text{C}$	50	A	
V_{CEK}	RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	V_{CES}		
t_{sc} (SCSOA)	$V_{CE} = V_{CES}$; $V_{GE} = \pm 15 \text{ V}$; $R_G = 47 \Omega$; $T_{VJ} = 125^\circ\text{C}$ non-repetitive	10	μs	
P_{tot}	$T_c = 25^\circ\text{C}$	208	W	

Symbol	Conditions	Characteristic Values ($T_{VJ} = 25^\circ\text{C}$, unless otherwise specified)		
		min.	typ.	max.
$V_{CE(sat)}$	$I_c = 50 \text{ A}$; $V_{GE} = 15 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	3.1 3.5	3.7 V	V
$V_{GE(th)}$	$I_c = 1 \text{ mA}$; $V_{GE} = V_{CE}$	4.5		6.5 V
I_{CES}	$V_{CE} = V_{CES}$; $V_{GE} = 0 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		1.1 mA 4.2 mA	
I_{GES}	$V_{CE} = 0 \text{ V}$; $V_{GE} = \pm 20 \text{ V}$		180 nA	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	Inductive load, $T_{VJ} = 125^\circ\text{C}$ $V_{CE} = 600 \text{ V}$; $I_c = 30 \text{ A}$ $V_{GE} = 15/0 \text{ V}$; $R_G = 47 \Omega$	100 70 500 70 4.6 3.4	ns ns ns ns mJ mJ	
C_{ies}	$V_{CE} = 25 \text{ V}$; $V_{GE} = 0 \text{ V}$; $f = 1 \text{ MHz}$	1.65		nF
R_{thJC} R_{thJH}	(per IGBT) with heatsink compound (0.42 K/m.K; 50 μm)	1.2	0.6 K/W K/W	

IXYS reserves the right to change limits, test conditions and dimensions.

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Features

- NPT IGBT technology
- low saturation voltage
- low switching losses
- square RBSOA, no latch up
- high short circuit capability
- positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- ultra fast free wheeling diodes
- solderable pins for PCB mounting
- package with copper base plate

Advantages

- space savings
- reduced protection circuits
- package designed for wave soldering

Typical Applications

- motor control
 - DC motor armature winding
 - DC motor excitation winding
 - synchronous motor excitation winding
- supply of transformer primary winding
 - power supplies
 - welding
 - X-ray
 - UPS
 - battery charger

Reverse diodes (FRED)

Symbol	Conditions	Maximum Ratings		
I _{F25}	T _C = 25°C	49	A	
I _{F80}	T _C = 80°C	31	A	

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V _F	I _F = 30 A; T _{VJ} = 25°C T _{VJ} = 125°C	2.4	2.7	V
		1.77		V
I _{RM}	I _F = 30 A; di _F /dt = 500 A/μs; T _{VJ} = 125°C	27		A
t _{rr}	V _R = 600 V; V _{GE} = 0 V	150		ns
R _{thJC}			1.3	K/W
R _{thJH}	with heatsink compound (0.42 K/m.K; 50 μm)	2.6		K/W

Temperature Sensor NTC

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R ₂₅	T = 25°C	455	470	kΩ
B _{25/50}			3474	K

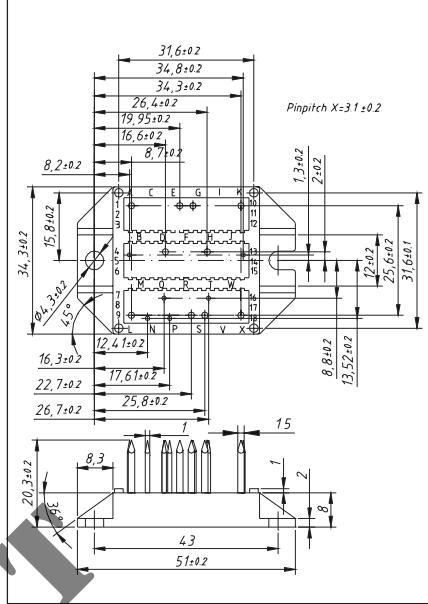
Module

Symbol	Conditions	Maximum Ratings		
T _{VJ}		-40...+150		°C
T _{stg}		-40...+150		°C
V _{ISOL}	I _{ISOL} ≤ 1 mA; 50/60 Hz	3000		V~
M _d	mounting torque (M4)	1.5 - 2.0		Nm
		14 - 18		lb.in.
a	Max. allowable acceleration	50		m/s ²

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
d _s	Creepage distance on surface (Pin to heatsink)	11.2		mm
d _A	Strike distance in air (Pin to heatsink)	11.2		mm

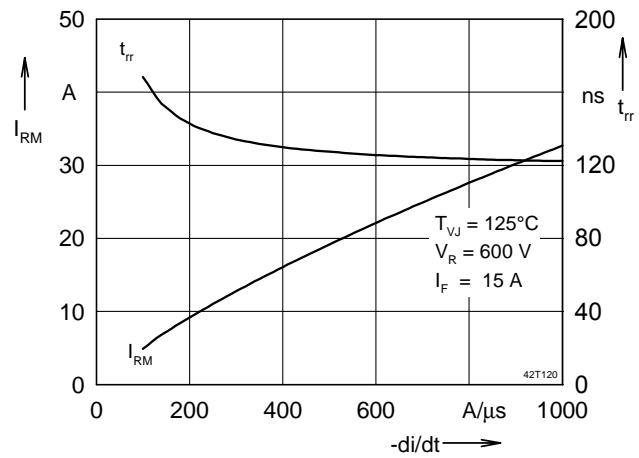
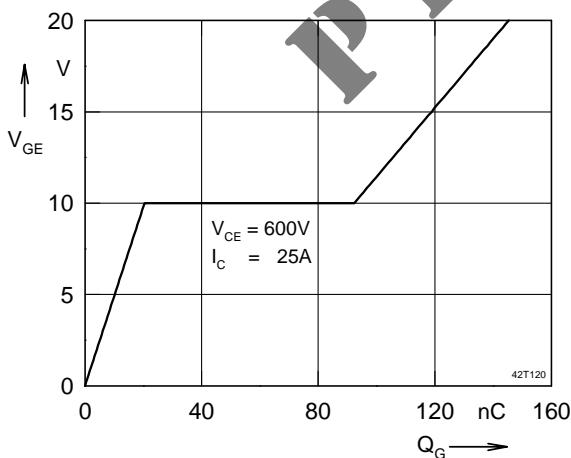
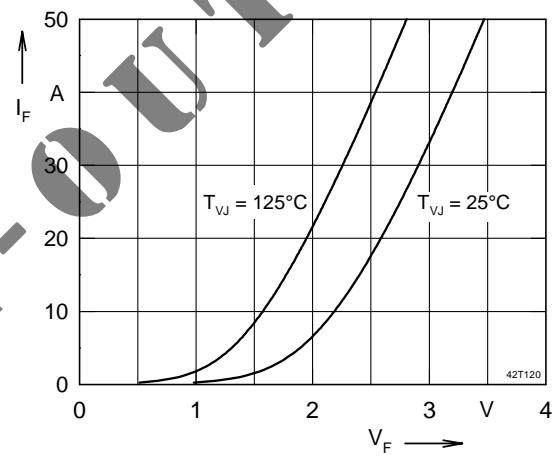
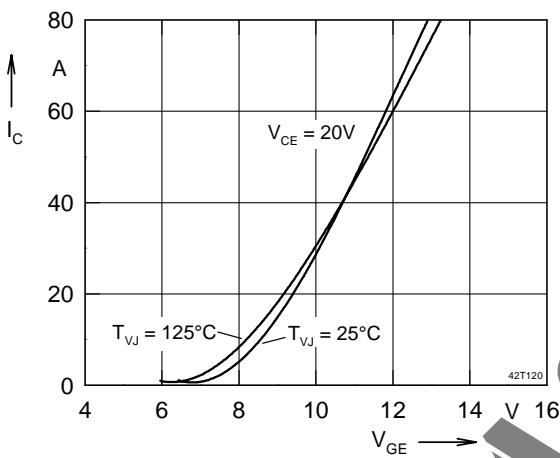
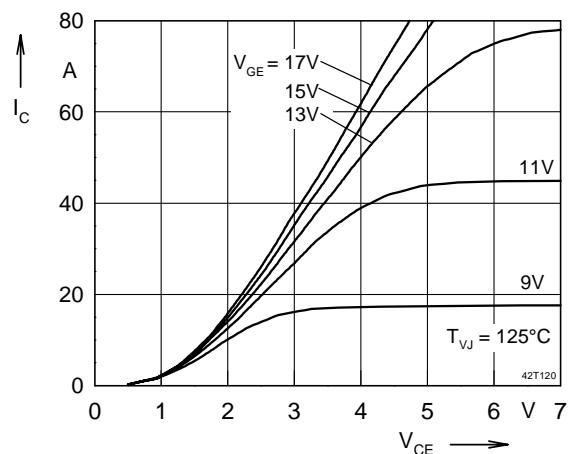
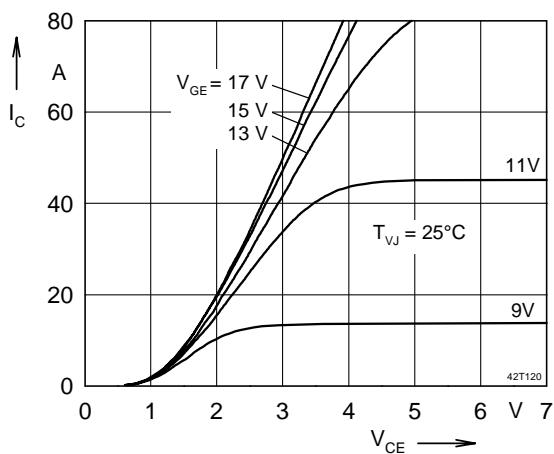
Weight		24	g

Dimensions in mm (1 mm = 0.0394")



Data according to IEC 60747 and refer to a single transistor or diode unless otherwise stated.

IXYS reserves the right to change limits, test conditions and dimensions.



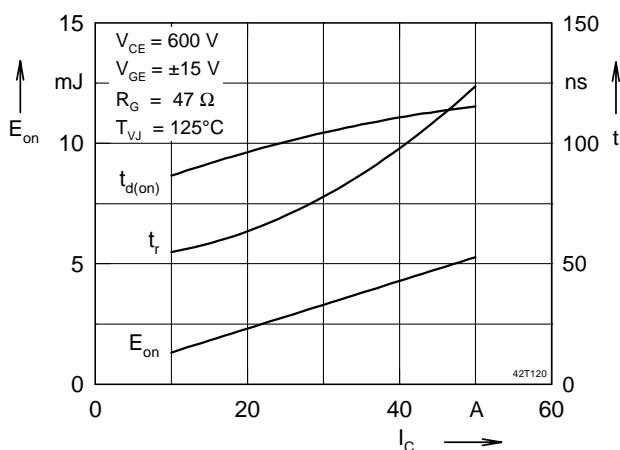


Fig. 7 Typ. turn on energy and switching

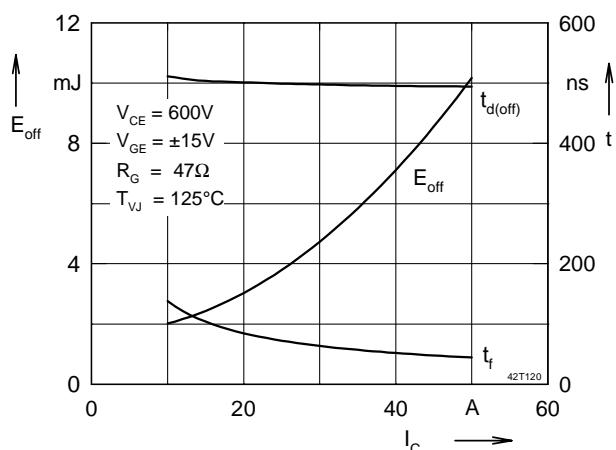


Fig. 8 Typ. turn off energy and switching times versus collector current times versus collector current

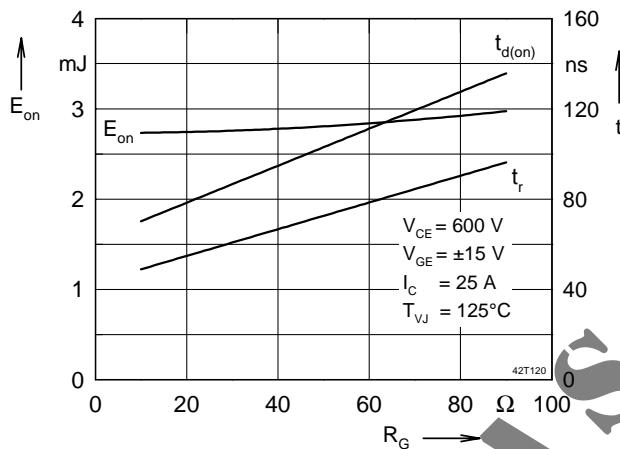


Fig. 9 Typ. turn on energy and switching

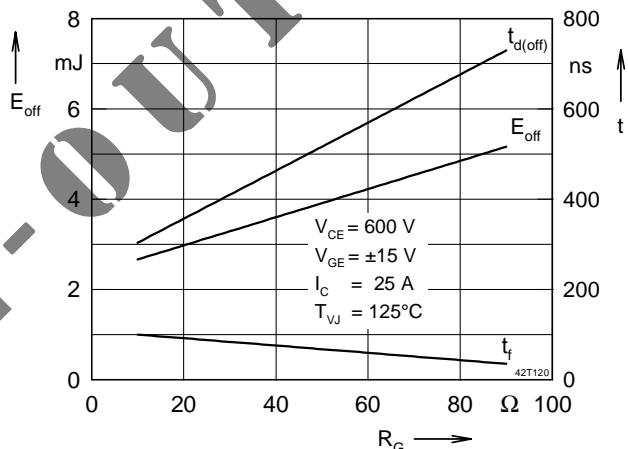


Fig. 10 Typ. turn off energy and switching times versus gate resistor times versus gate resistor

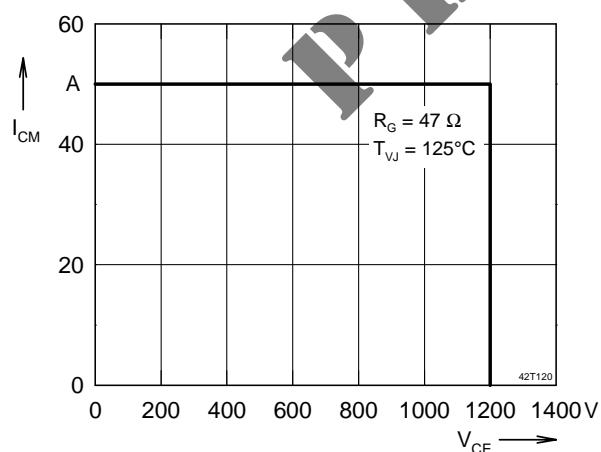


Fig. 11 Reverse biased safe operating area

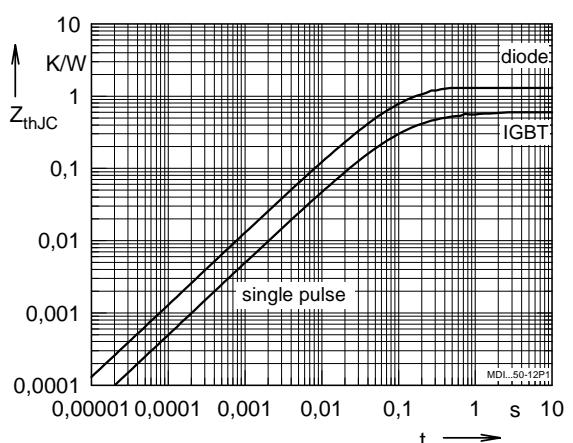


Fig. 12 Typ. transient thermal impedance RBSOA